



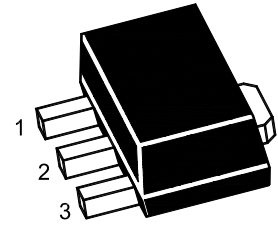
# TN04P30SQ

## P-Channel Enhancement Mode Power MOSFET

### Features

- High density cell design for ultra low  $R_{DS(on)}$
- Excellent package for good heat dissipation
- $V_{DS} = -30V, I_D = -4.1A$   
 $R_{DS(on)} < 65m\Omega @ V_{GS} = -10V$

### SOT-89



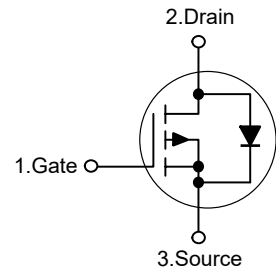
1. Gate 2.Drain 3.Source

Marking Code: 04P30

### Applications

- Power Switching Application

### Schematic Diagram



### Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$-I_D$	4.1	A
Drain Current-Pulsed <sup>Note1</sup>	$-I_{DM}$	20	A
Maximum Power Dissipation	$P_D$	1.3	W
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	$T_{STG}$	-55 to +150	°C

### Thermal Characteristics

Maximum Junction-to-Case <sup>Note2</sup>	$R_{\theta JC}$	96	°C/W
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### Electrical Characteristics

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$-V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	$-I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	--	--	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	--	--	$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$-V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	0.7	0.9	1.3	V
Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-4.1A$	--	48	65	m $\Omega$
		$V_{GS}=-4.5V, I_D=-3A$	--	56	85	m $\Omega$
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=-5V, I_D=-4.1A$	--	10	--	S
Dynamic Characteristics						
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	--	880	--	pF
Output Capacitance	$C_{oss}$		--	105	--	pF
Reverse Transfer Capacitance	$C_{rss}$		--	65	--	pF
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, I_D=-4.1A,$ $V_{GS}=-10V, R_G=6\Omega$	--	7	--	nS
Turn-on Rise Time	$t_r$		--	3	--	nS
Turn-off Delay Time	$t_{d(off)}$		--	30	--	nS
Turn-off Fall Time	$t_f$		--	12	--	nS
Total Gate Charge	$Q_g$	$V_{DS}=-15V,$ $I_D=-4.1A, V_{GS}=-4.5V$	--	8.5	--	nC
Gate-Source Charge	$Q_{gs}$		--	1.8	--	nC
Gate-Drain Charge	$Q_{gd}$		--	2.7	--	nC
Source-Drain Diode Characteristics						
Diode Forward Voltage <sup>Note3</sup>	$-V_{SD}$	$V_{GS}=0V, I_S=-4.1A$	--	--	1.2	V
Diode Forward Current <sup>Note2</sup>	$-I_S$		--	--	4.1	A

Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

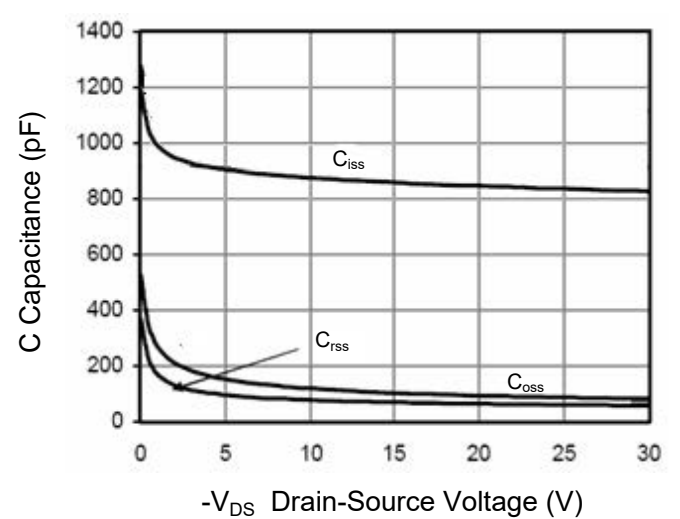
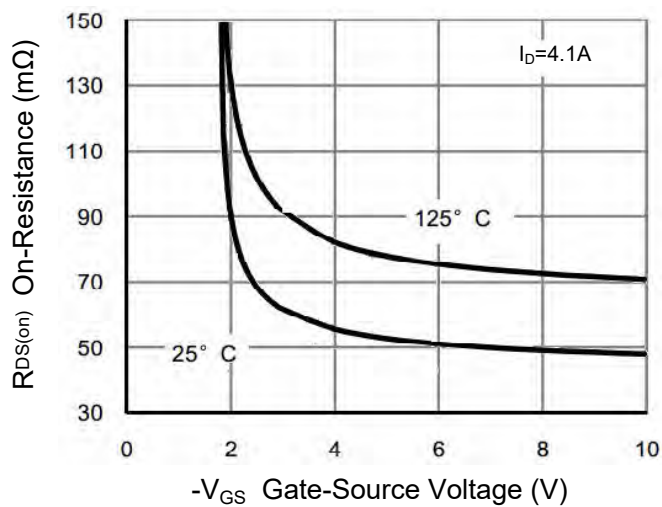
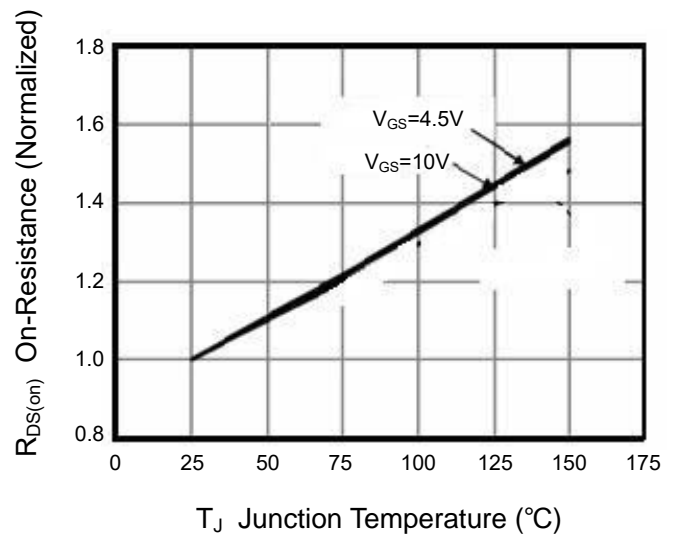
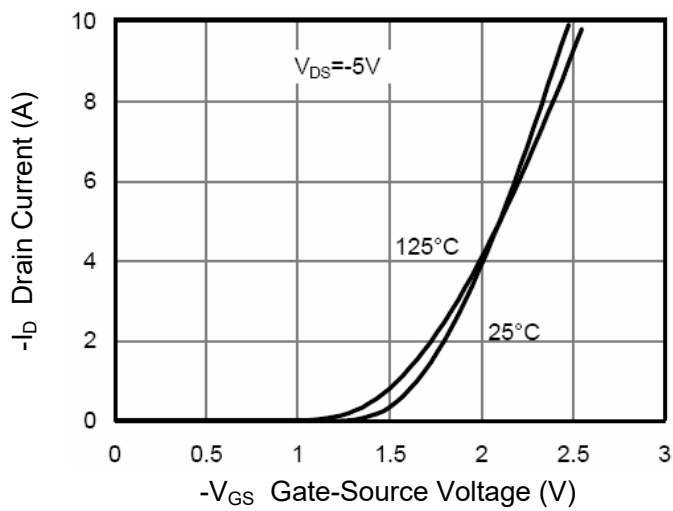
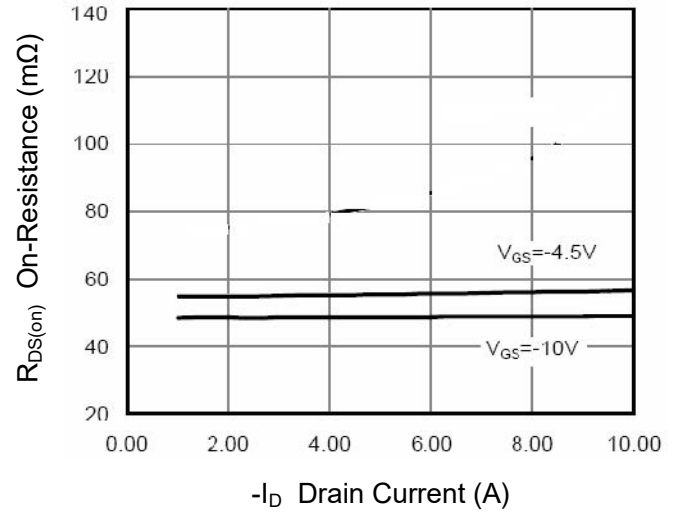
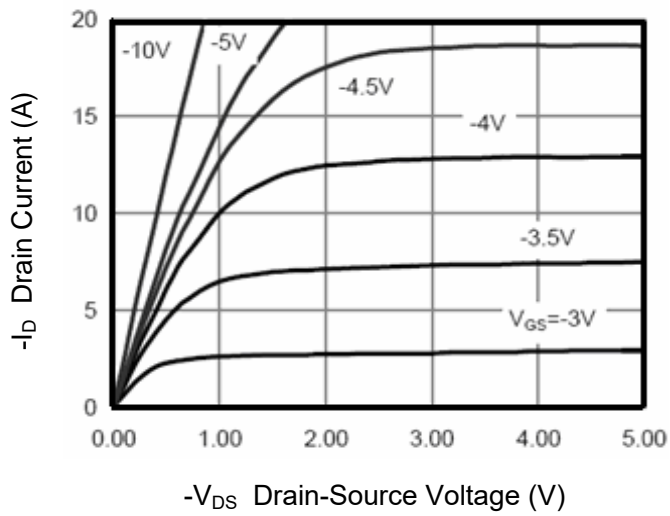
3. Pulse Test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .



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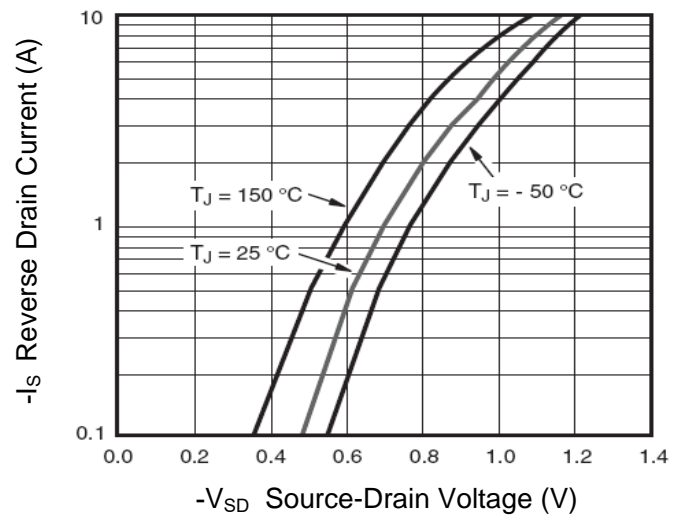
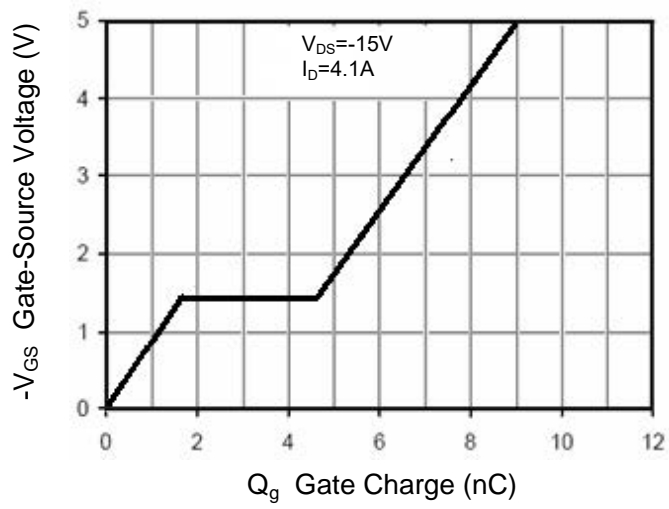
### Typical Characteristic Curves





# TN04P30SQ

## P-Channel Enhancement Mode Power MOSFET

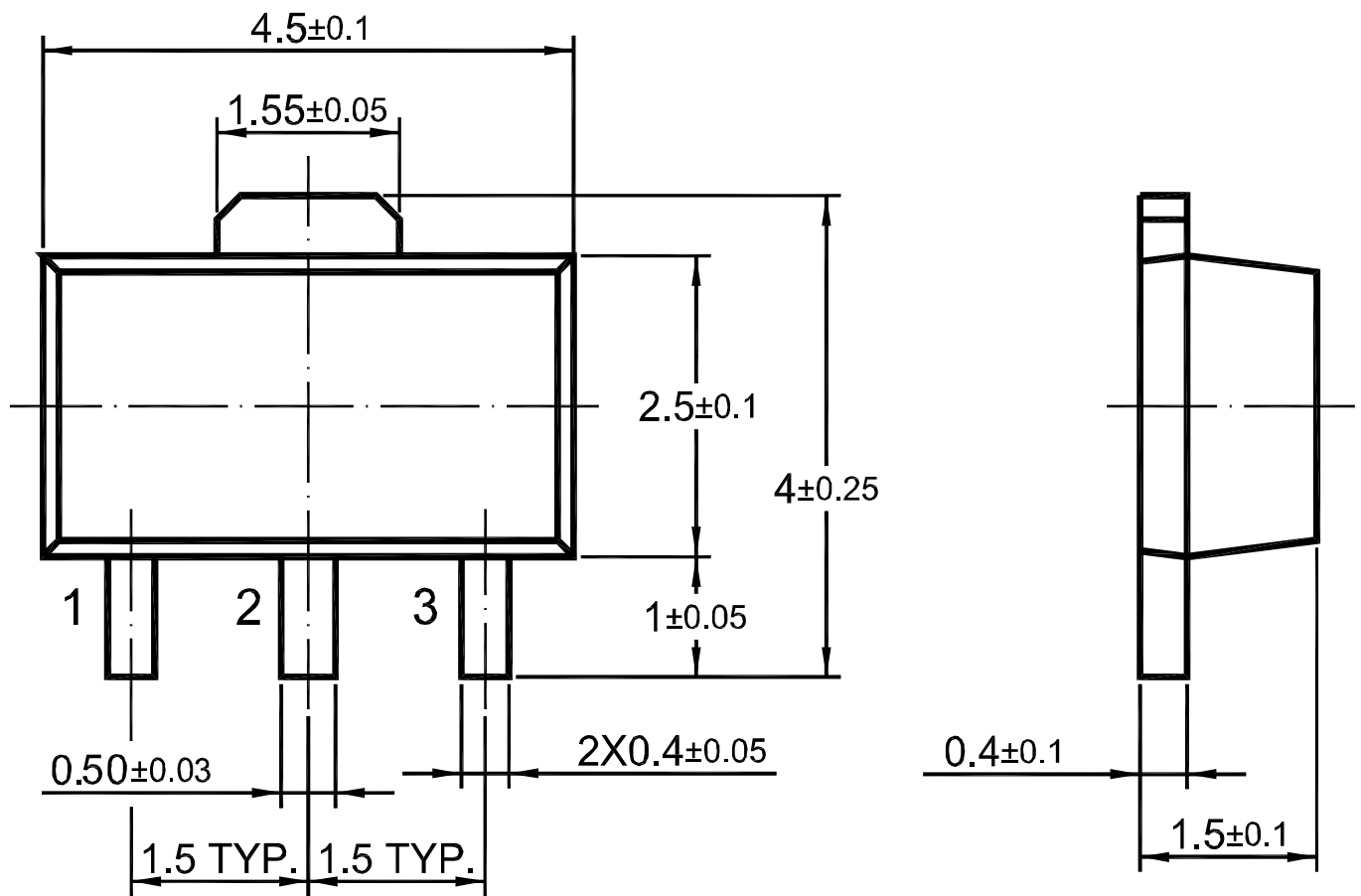




### Package Outline

SOT-89

Dimensions in mm



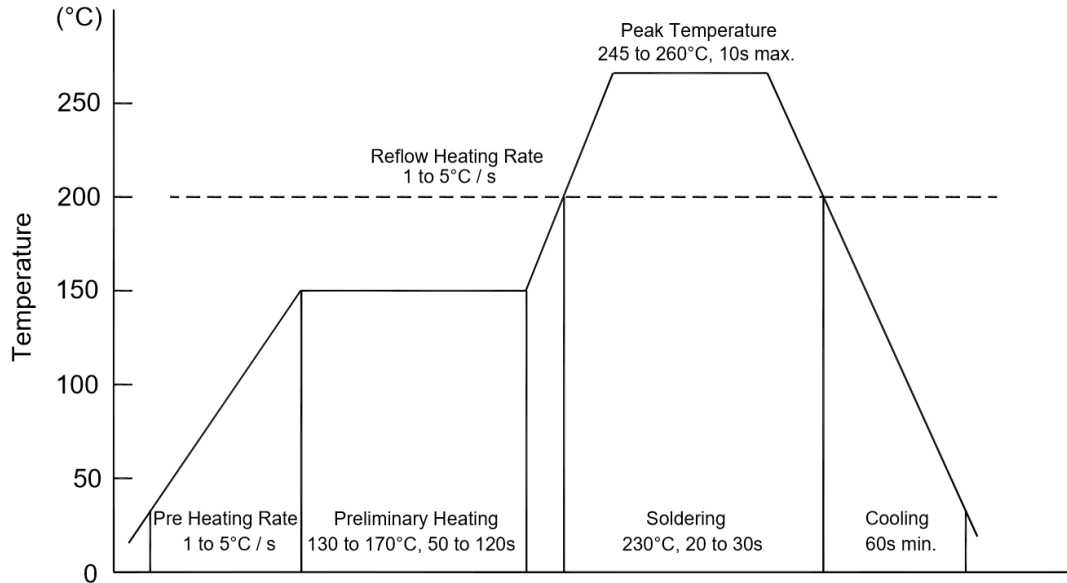
### Ordering Information

Device	Package	Shipping
TN04P30SQ	SOT-89	1,000PCS/Reel&7inches
		3,000PCS/Reel&13inches



### Conditions of Soldering and Storage

#### ◆ Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

#### ◆ Conditions of hand soldering

- Temperature: 370 °C
- Time: 3s max.
- Times: one time

#### ◆ Storage conditions

- **Temperature**  
5 to 40 °C
- **Humidity**  
30 to 80% RH
- **Recommended period**  
One year after manufacturing

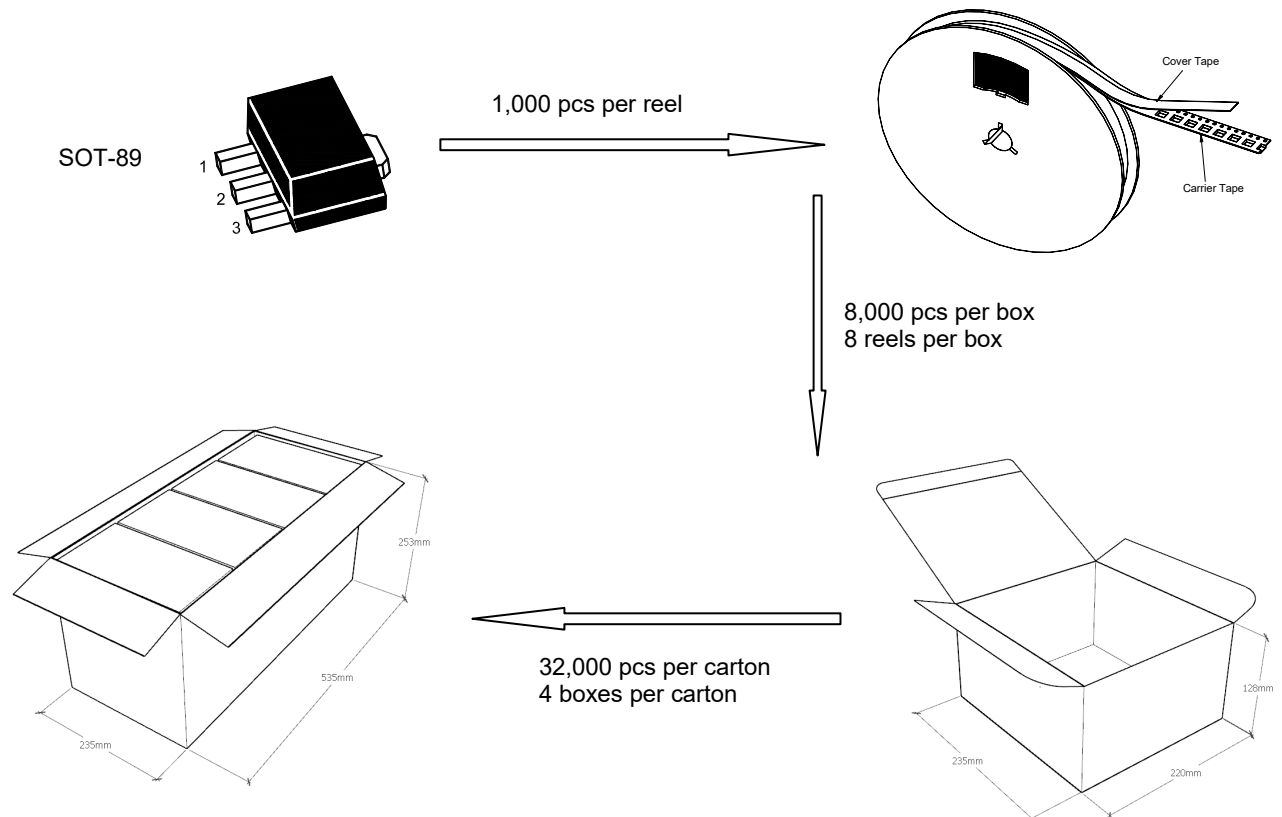


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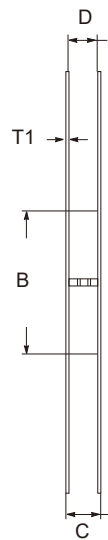
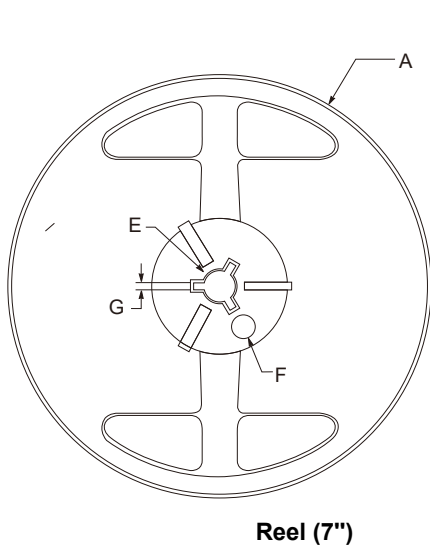
## P-Channel Enhancement Mode Power MOSFET

### Package Specifications

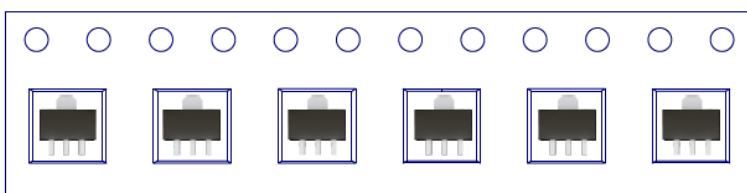
- The method of packaging (1,000PCS/Reel&7inches)



### ◆ Embossed tape and reel data



symbol	Value(unit:mm)
A	$\Phi 179 \pm 1$
B	$60.5 \pm 0.2$
C	$15.3 \pm 0.3$
D	$12.5 \sim 13.7$
E	$\Phi 13.5 \pm 0.2$
F	$\Phi 10.0 \pm 0.2$
G	$2.7 \pm 0.2$
T1	$1.0 \pm 0.2$



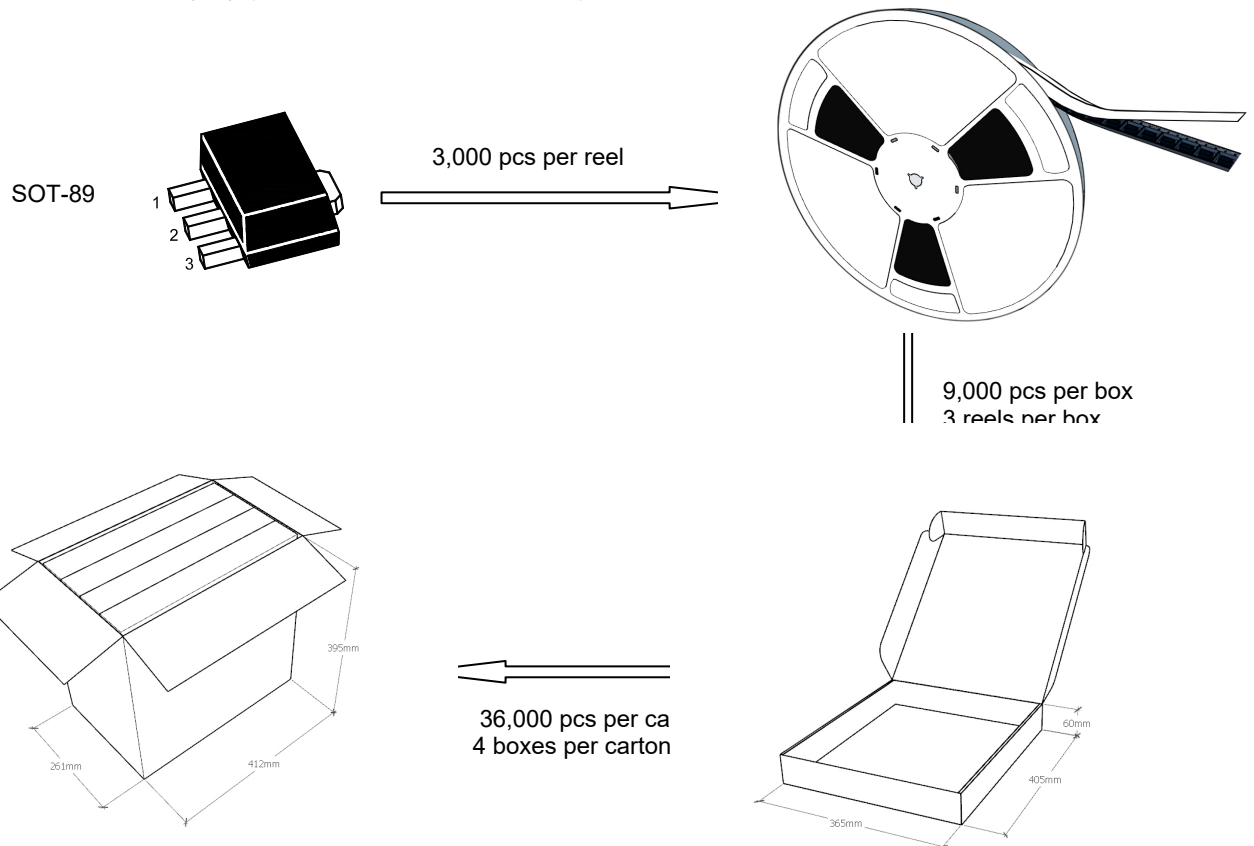


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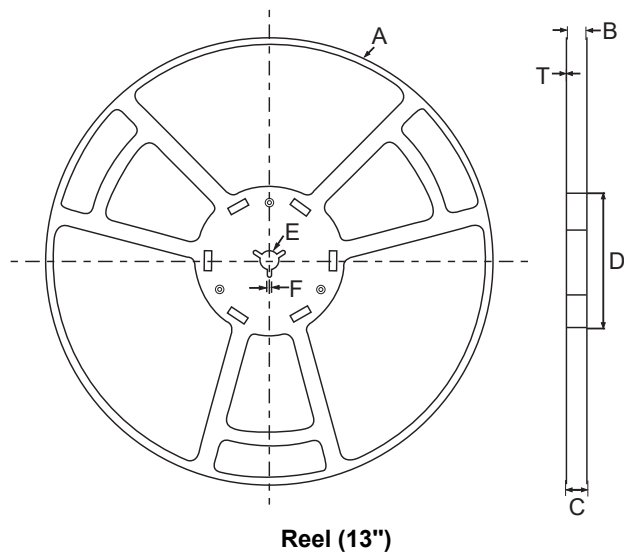
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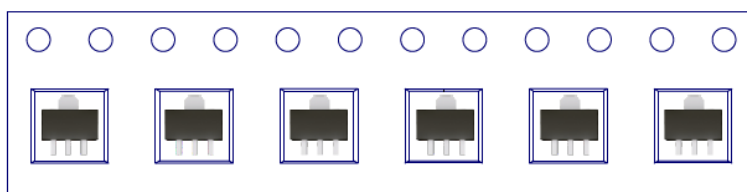
- The method of packaging (3,000PCS/Reel&13inches)



### ◆ Embossed tape and reel data



symbol	Value(unit:mm)
A	$\Phi 330 \pm 1$
B	$12.7 \pm 0.5$
C	$16.5 \pm 0.3$
D	$\Phi 99.5 \pm 0.5$
E	$\Phi 13.6 \pm 0.3$
F	$2.8 \pm 0.3$
T1	$1.9 \pm 0.2$








### Contact Information

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For additional information, please contact your local Sales Representative.

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